

Performance Curves MBN MBNA

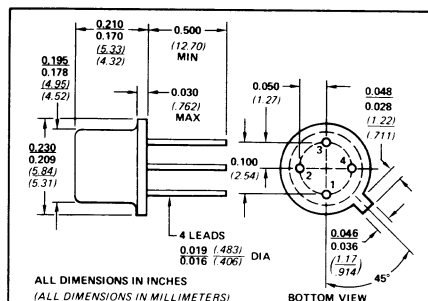
See Pages 4-7, 9



N-CHANNEL ENHANCEMENT-TYPE SILICON MOS FIELD-EFFECT TRANSISTOR

**NORMALLY-OFF MOS FETS FOR AMPLIFIERS
ANALOG AND DIGITAL SWITCHING APPLICATIONS**

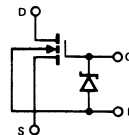
- Low I_{GSS}
- Integrated Zener Clamp Protects the M116 Gate



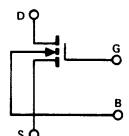
TO-72

ABSOLUTE MAXIMUM RATINGS (25°C)

Drain-to-Source Voltage	30 V
Gate-to-Source Voltage M116	30 V
Gate-to-Source Voltage M117	±50 V
Gate-to-Drain Voltage M116	30 V
Gate-to-Drain Voltage M117	±50 V
Drain Current	50 mA
Gate Zener Current ... M116	±0.1 mA
Storage Temperature	-65 to 150°C
Operating Junction Temperature	-55 to +125°C
Total Device Dissipation (Derate 2.25 mW/°C to 125°C)	225 mW



M116	
PIN	OUT
1	D
2	G
3	B,C
4	S



M117	
PIN	OUT
1	S
2	G
3	D
4	B,C

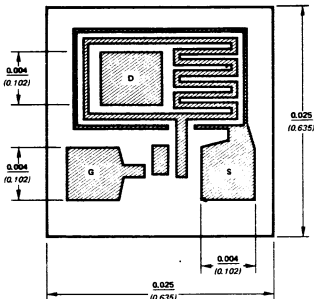
ELECTRICAL CHARACTERISTICS (25°C unless otherwise noted)

Characteristic	M116		M117		Unit	Test Condition
	Min	Max	Min	Max		
1 I_{GSS} Gate-Body Leakage		100		1.0	pA	$V_{GS} = 20 V, V_{DS} = V_{BS} = 0$
2 $V_{GS(th)}$ Gate Threshold Voltage	1	5	1	5	V	$V_{GS} = V_{DS}, I_D = 10 \mu A, V_{BS} = 0$
3 BV_{DSS} Drain-Source Breakdown Voltage	30		30			$I_D = 1 \mu A, V_{GS} = V_{BS} = 0$
4 BV_{SDS} Source-Drain Breakdown Voltage	30		30			$I_S = 1 \mu A, V_{GD} = V_{BD} = 0$
5 BV_{GBS} Gate-Body Breakdown Voltage	30	60	±100 ¹			$I_G = 10 \mu A, V_{SB} = V_{DB} = 0$
6 $I_{D(off)}$ Drain Cutoff Current		10		10	nA	$V_{DS} = 20 V, V_{GS} = V_{BS} = 0$
7 $I_{S(off)}$ Source Cutoff Current		10		10		$V_{SD} = 20 V, V_{GD} = V_{BD} = 0$
8 $I_{D(on)}$ ON Drain Current	2	20	2	20	mA	$V_{GS} = V_{DS} = -10 V, V_{BS} = 0$
9 $r_{DS(on)}$ Drain Source ON Resistance		100		100	Ω	$V_{GS} = 20 V, I_D = 100 \mu A, V_{BS} = 0$
		200		200		$V_{GS} = 10 V, I_D = 100 \mu A, V_{BS} = 0$
11 C_{iss} Input Capacitance		10		8	pF	$V_{GB} = 0, V_{DB} = 10 V, V_{BS} = 0$
12 C_{gs} or C_{gd} Gate-Source or Gate-Drain Capacitance		2.5		2.5		$V_{GB} = V_{DB} = V_{SB} = 0$ Body Guarded
13 C_{db} Drain-Body Capacitance		7		7		$V_{GB} = 0, V_{DB} = 10 V$
		MBN		MBNA		$f = 1 \text{ MHz}$

Note:

1 Gate -oxide breakdown voltage.

BODY IS BACKSIDE CONTACT



ALL DIMENSIONS IN INCHES.
ALL DIMENSIONS IN MILLIMETERS.

N-CHANNEL ENHANCEMENT-TYPE SILICON MOS FIELD-EFFECT TRANSISTOR

APPLICATIONS

- Audio Amplifiers
- Analog Circuits
- Digital Switching Circuits
- Commutating Circuits

PRINCIPAL DEVICE

M116

PACKAGE TYPE

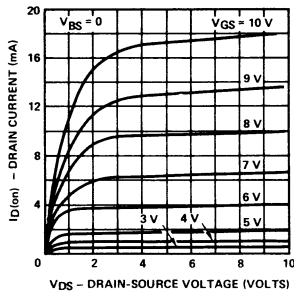
TO-72

FEATURES

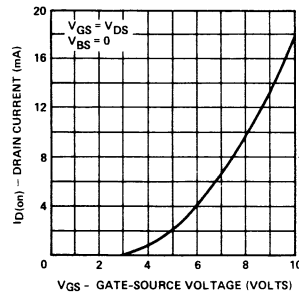
- Integrated Zener Clamp Protects the Gate
- Normally OFF

PERFORMANCE CURVES (25°C unless otherwise noted)

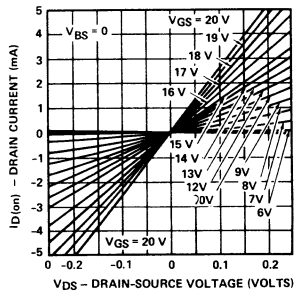
Output Characteristics



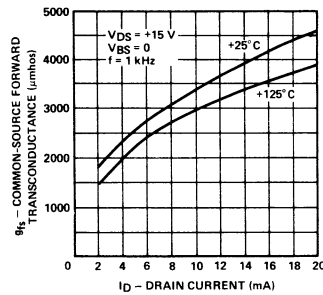
Transfer Characteristic



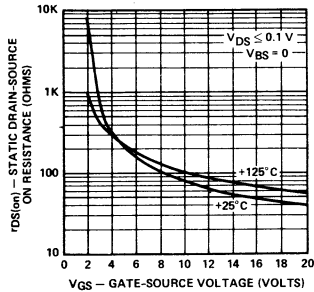
Low Voltage Output Characteristics



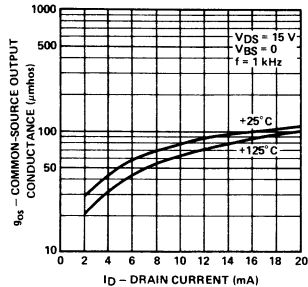
Forward Transconductance vs Drain Current



Drain-Source ON State Resistance vs Gate-Source Bias

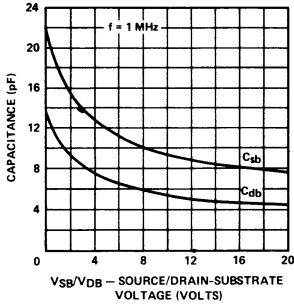


Output Conductance vs Drain Current

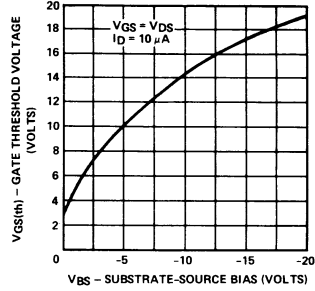


PERFORMANCE CURVES (Cont'd) (25°C unless otherwise noted)

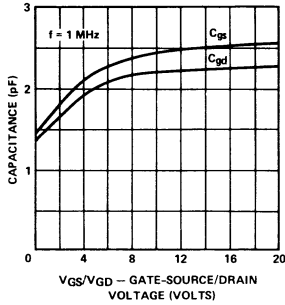
Substrate Capacitance vs Voltage



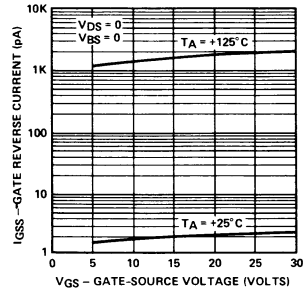
Gate Threshold Voltage vs Substrate Bias



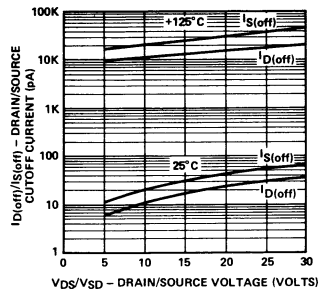
Gate Capacitance vs Voltage

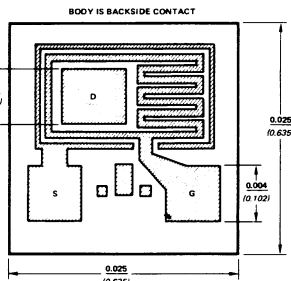


Gate Leakage Current vs Gate-Source Bias



Source-Drain Leakage Currents vs Voltage





ALL DIMENSIONS IN INCHES.
ALL DIMENSIONS IN MILLIMETERS.

N-CHANNEL ENHANCEMENT-TYPE SILICON MOS FIELD-EFFECT TRANSISTOR

APPLICATIONS

- Audio Amplifiers
- Analog Circuits
- Digital Switching Circuits
- Commutating Circuits

FEATURES

- Ultra-Low Gate Leakage
- Normally OFF

PRINCIPAL DEVICE

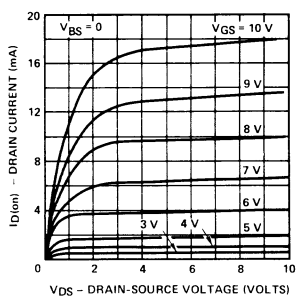
M117

PACKAGE TYPE

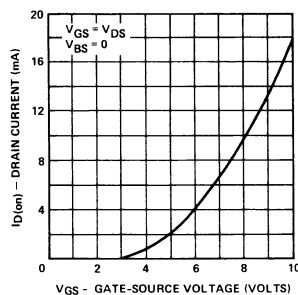
TO-72

PERFORMANCE CURVES (25°C unless otherwise noted)

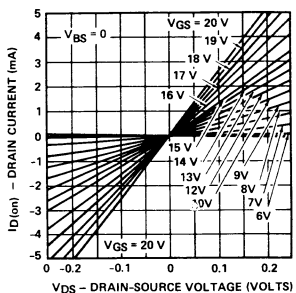
Output Characteristics



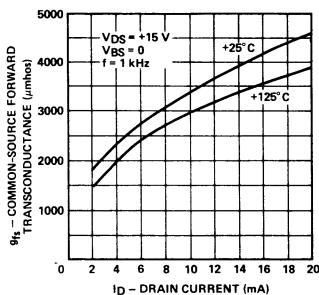
Transfer Characteristic



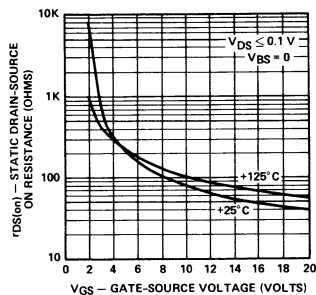
Low Voltage Output Characteristics



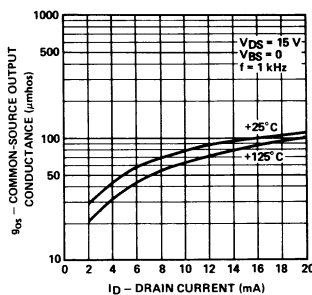
Forward Transconductance vs Drain Current



Drain-Source ON State Resistance vs Gate-Source Bias

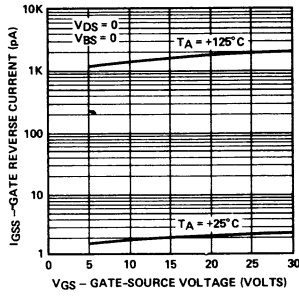


Output Conductance vs Drain Current

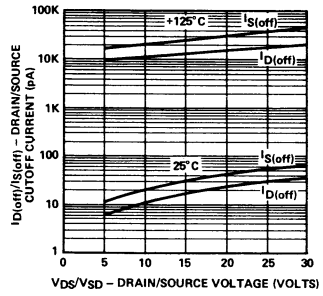


PERFORMANCE CURVES (Cont'd) (25°C unless otherwise noted)

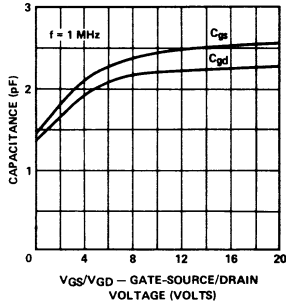
Gate Leakage Current vs Gate-Source Bias



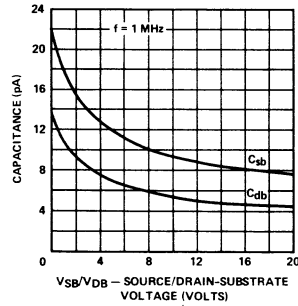
Source-Drain Leakage Currents vs Voltage



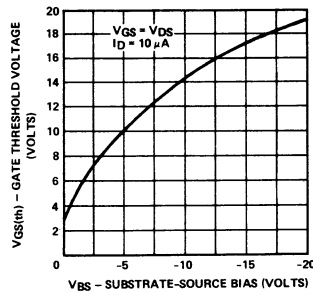
Gate Capacitance vs Voltage



Substrate Capacitance vs Voltage



Gate Threshold Voltage vs Substrate Bias



Performance Curves ME

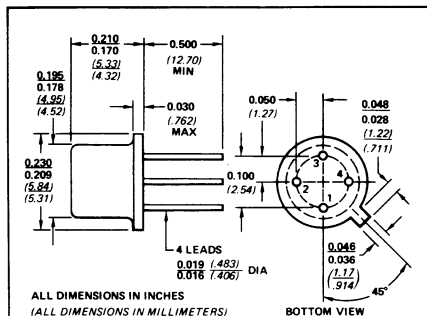
See Page 4-13



P-CHANNEL ENHANCEMENT-TYPE SILICON MOS FIELD-EFFECT TRANSISTOR

HIGH VOLTAGE MOSFET TRANSISTOR FOR ANALOG AND DIGITAL SWITCHING APPLICATIONS

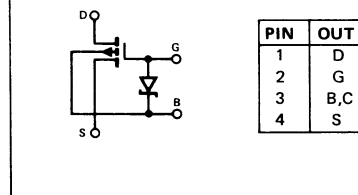
- Zener Clamp Protects the Gate
- Low Drain-Source ON Resistance
- Very Low $I_{D(off)}$ and $I_{S(off)}$



TO-72

ABSOLUTE MAXIMUM RATINGS (25°C)

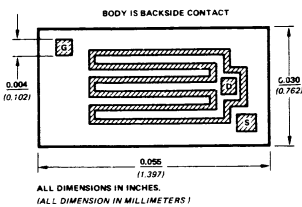
Drain-to-Source Voltage	±75 V
Gate-to-Source Voltage	-80 V
Gate-to-Drain Voltage	-80 V
Drain Current	-50 mA
Gate Zener Current	±0.1 mA
Storage Temperature	-65 to +150°C
Operating Junction Temperature	-55 to +125°C
Total Device Dissipation (Derate 2.25 mW/°C to 125°C)	225 mW



ELECTRICAL CHARACTERISTICS (25°C unless otherwise noted)

Characteristic		Min	Max	Unit	Test Conditions	
S T A T I C	1 BV _{DSS} Drain-Source Breakdown Voltage	-75		V	$I_D = -1 \mu A, V_{GS} = V_{BS} = 0$	
	2 BV _S _{DS} Source-Drain Breakdown Voltage	-75			$I_S = -1 \mu A, V_{DG} = V_{BD} = 0$	
	3 BV _G _{BS} Gate-Body Breakdown Voltage	-80			$I_G = -10 \mu A, V_{SB} = V_{DB} = 0$	
	4 IG _{SS} Gate-Body Leakage		-250	pA	$V_{GS} = -50 V, V_{DS} = V_{BS} = 0$	
	5 ID(off) Drain Cutoff Current		-0.8	nA	$V_{DS} = -50 V, V_{GS} = V_{BS} = 0$	
	6 IS(off) Source Cutoff Current		-0.8	nA	$V_{SB} = -50 V, V_{GD} = V_{BD} = 0$	
	7 VGS(th) Gate Threshold Voltage	-2	-6	V	$V_{GS} = V_{DS}, I_D = -10 \mu A, V_{BS} = 0$	
	8 9 10	r _{DS(on)} Drain-Source ON Resistance		90	Ω	$V_{GS} = -80 V, I_D = -100 \mu A, V_{BS} = 0 V$
				125		$V_{GS} = -60 V, I_D = -100 \mu A, V_{BS} = 20 V$
				230		$V_{GS} = -40 V, I_D = -100 \mu A, V_{BS} = 40 V$
11 12 13 14	C _{gs} or C _{gd} Gate-Source or Gate-Drain Capacitance		8	pF	$V_{GS} = 0, V_{DS} = 0, V_{BS} = 0$ Body Guarded	
			15		$V_{GB} = 0, V_{DS} = 0, V_{SB} = -5 V$	
	C _{sb} Source-Body Capacitance		10		$V_{GB} = 0, V_{DB} = -5 V, V_{SB} = -5 V$ Body Guarded	
	C _{ds} Drain-Source Capacitance		0.3			

ME



P-CHANNEL ENHANCEMENT-TYPE SILICON MOS FIELD-EFFECT TRANSISTOR

APPLICATIONS

- Analog and Digital Switching
- Multiplexers

FEATURES

- Integrated Zener Clamp Protects the Gate
- High Voltage Breakdown
- Low $I_{D(off)}$ and $I_{S(off)}$

PRINCIPAL DEVICE

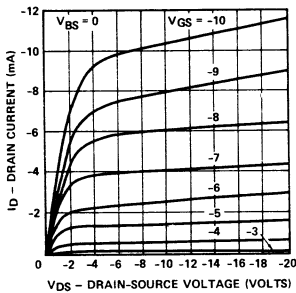
M119

PACKAGE TYPE

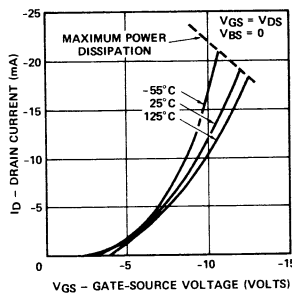
TO-72

PERFORMANCE CURVES (25°C unless otherwise noted)

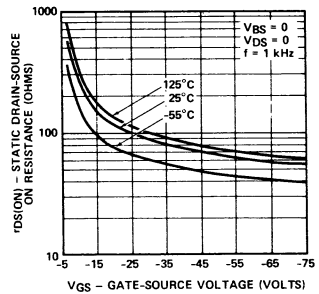
Output Characteristic



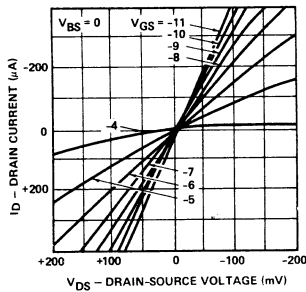
Transfer Characteristics



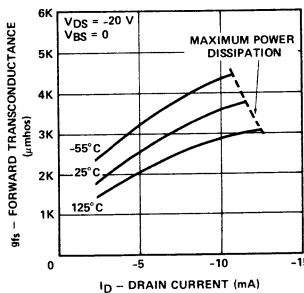
Drain Source ON Resistance vs Gate-Source Bias



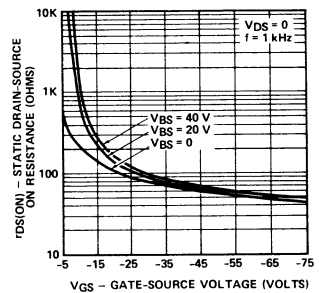
Low Voltage Output Characteristics



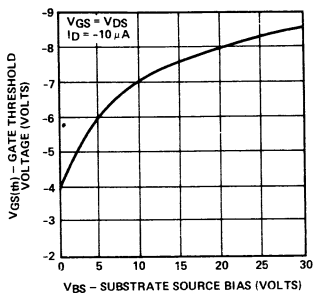
Forward Transconductance vs Drain Current



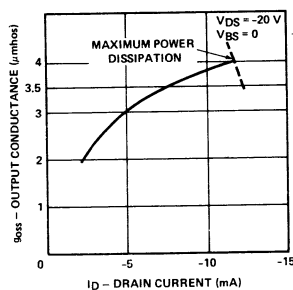
Drain-Source ON Resistance vs Gate-Source Bias



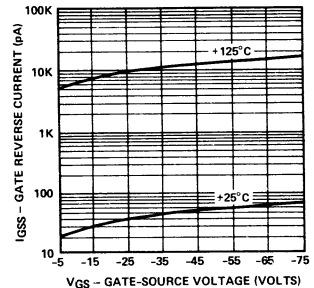
Gate Threshold Voltage vs Substrate Bias



Output Conductance vs Drain Current



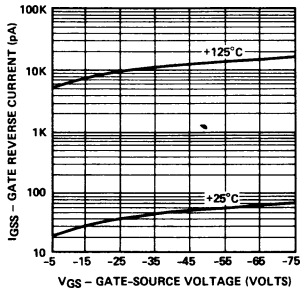
Gate Leakage Current vs Gate-Source Bias



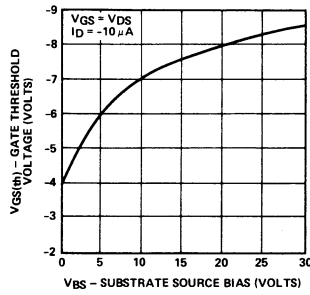
4

PERFORMANCE CURVES (Cont'd) (25°C unless otherwise noted)

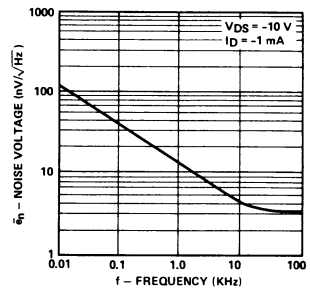
Gate Leakage Current vs Gate-Source Bias



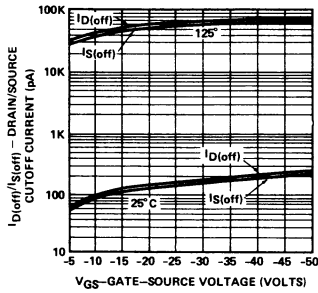
Gate Threshold Voltage vs Substrate Bias



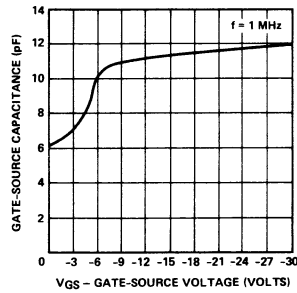
Short Circuit Equivalent Input Noise Voltage vs Frequency



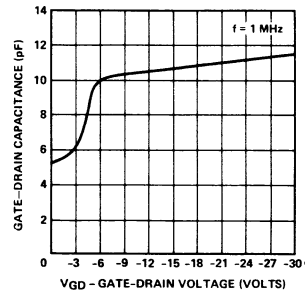
Drain/Source Leakage Currents vs Voltage



Gate-Source Capacitance vs Voltage



Gate-Drain Capacitance vs Voltage



Performance Curves MKA

See Page 4-15



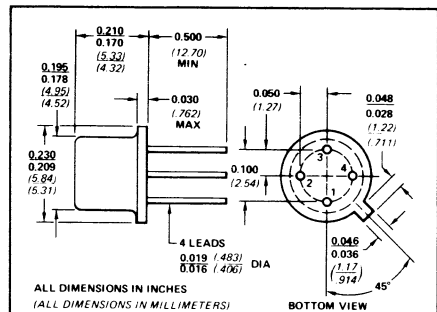
P-CHANNEL ENHANCEMENT-TYPE SILICON MOS FIELD-EFFECT TRANSISTOR

FOR AUDIO & RF-AMPLIFIERS, CHOPPER, MULTIPLEX AND COMMUTATING APPLICATIONS

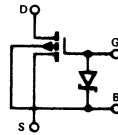
- Integrated Zener Clamp Protects the Gate
- Normally OFF with Zero Gate Voltage

ABSOLUTE MAXIMUM RATINGS (25°C)

Drain-to-Source Voltage	-30 V
Gate-to-Source Voltage	-30 V
Gate-to-Drain Voltage	-30 V
Drain Current	-50 mA
Gate Current (Forward Direction for Zener Clamp)	+0.1 mA
Storage Temperature	-65 to 150°C
Operating Junction Temperature	-55 to 125°C
Total Dissipation at 25°C Ambient Temperature (Derate 2.25 mW/°C)	225 mW



TO-72



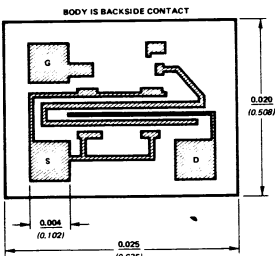
PIN	OUT
1	D
2	G
3	B, C
4	S

ELECTRICAL CHARACTERISTICS (25°C unless otherwise noted)

Characteristic	Min	Typ	Max	Unit	Test Conditions	
1 I _{GSS} Gate Leakage Current			-1	nA	V _{GS} = -15 V, V _{DS} = V _{BS} = 0	
2 BV _{DSS} Drain-Source Breakdown Voltage	-30			V	I _D = -10 μA, V _{GS} = V _{BS} = 0	
3 V _{GS(th)} Gate Threshold Voltage	-3		-6		V _{GS} = V _{DS} , I _D = -10 μA, V _{BS} = 0	
4 I _{DSS} Drain Leakage Current		-0.5	-10	nA	V _{DS} = -20 V, V _{GS} = V _{BS} = 0	
5 I _{D(on)} Drain Current	-3	-6		mA	V _{GS} = V _{DS} = -10 V, V _{BS} = 0	
6 r _{DS(on)} Drain-Source ON Resistance			300	Ω	V _{GS} = -15 V, I _D = -0.1 mA, V _{BS} = 0	
7 g _{fs} Common Source Forward Transconductance	1,000			μmho	V _{GS} = V _{DS} = -10 V, V _{BS} = 0	
8 C _{gs} Gate-Source Capacitance			3	pF		f = 1 kHz
9 C _{gd} Gate-Drain Capacitance			2.5			f = 10 MHz
10 C _{ds} Drain-Source Capacitance		0.15				f = 1 MHz
11						

MKA

P-CHANNEL ENHANCEMENT-TYPE SILICON MOS FIELD-EFFECT TRANSISTOR



ALL DIMENSIONS IN INCHES
(ALL DIMENSIONS IN MILLIMETERS)

APPLICATIONS

- Audio and RF Amplifiers
- Analog Switches
- Logic Circuits
- Multiplexers

PRINCIPAL DEVICE

MEM511

PACKAGE TYPE

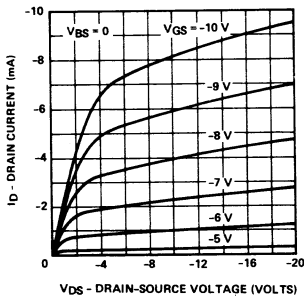
TO-72

FEATURES

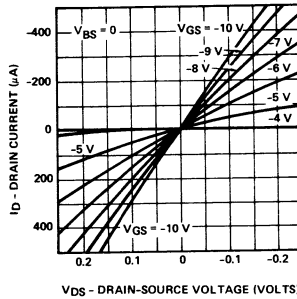
- $10^{10} \Omega$ Input Resistance
- Integrated Zener Clamp Protects the Gate
- Square Low Transfer Characteristics
- Normally OFF

PERFORMANCE CURVES (25°C unless otherwise noted)

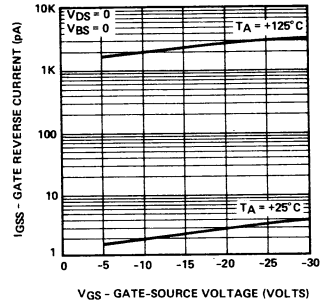
Output Characteristics



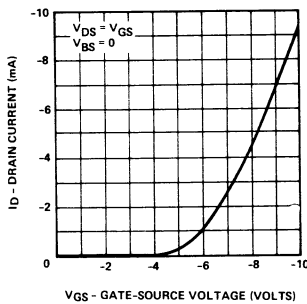
Low Voltage Output Characteristics



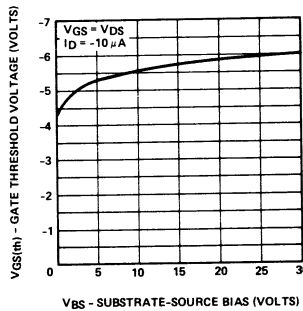
Gate Leakage Current vs Gate-Source Bias



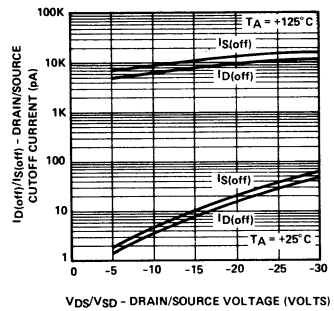
Transfer Characteristic



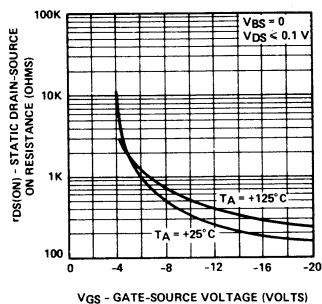
Gate Threshold Voltage vs Substrate Bias



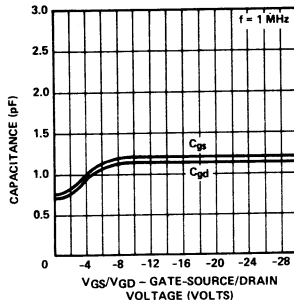
Source-Drain Leakage Currents vs Voltage



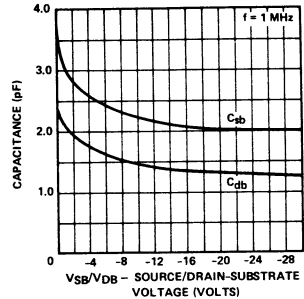
Drain-Source ON State Resistance vs Gate-Source Bias



Gate Capacitance vs Voltage



Substrate Capacitance vs Voltage



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